IEEE P802.3cw Task Force 15 Nov 2021 Plenary Teleconference Meeting
Unapproved Meeting Minutes, Prepared by John D'Ambrosia
Meeting called to order at 10:03 am ET (all times ET) by John D'Ambrosia, who was chairing the meeting.

Chair noted that individuals should fill out IMAT information for attendance.

Presentation #1	**Agenda and General Information**
Presenter:	John D'Ambrosia
URL:	https://www.ieee802.org/3/cw/public/21_11/agenda_3cw_211115.pdf

The chair asked if there were any objections to the agenda. There were no other objections to anything on the agenda, and it was considered approved.

Minutes –
25 Oct - https://www.ieee802.org/3/cw/public/tf_interim/21_1025/minutes_3cw_211025_unapproved.pdf

Chair asked if there were any corrections – there were none. Chair asked if there were any objections to approving the noted meeting minutes – there were none, and the minutes were considered approved.

Chair shared slide #3 which discussed non-payment of registration fees

Chair noted that the agenda deck had been sent out, and requested that individuals review the following IEEE SA policies prior to the interim meeting –

- IEEE SA Participation Policy
- IEEE SA Copyright Policy
- IEEE SA Patent Policy

Chair asked if anyone needed any of these policies reviewed in-depth. There were no requests.

Chair presented the second slide (See Slide #23) of the IEEE SA Participation Policy slides. Chair noted – "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Chair presented the third slide (See Slide #28) of the IEEE SA Patent Policy slides. Chair did call for Potentially Essential Patents, and no one came forward.

Chair presented the second slide (See Slide #33) of the IEEE SA Copyright Polic slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Presentation #2	**Chief Editor's Report**
Presenter	Tom Issenhuth
URL	https://www.ieee802.org/3/cw/public/21_11/issenhuth_3cw_01_211115.pdf

The Chief Editor noted that request to pull 2 comments (21 and 23) form the bucket had been received.

There were no questions or discussion.

Consideration of comment submitted against D1.2 began at approximately 10:15am, led by the Chief Editor.

During consideration of Comment #8, 9, 10, and 11, the following presentation was heard.

Presentation #3	**In Support of comments #8, 9, 10, 11 against D1.2**
Presenter	David Lewis
URL	https://www.ieee802.org/3/cw/public/21_11/lewis_3cw_01a_211115.pdf

Consideration of comment submitted against D1.2 ended at 11:47am, led by the Chief Editor.
An update report on the status of comment responses will be uploaded to the 802.3cw comment webpage.

Presentation #4	**ROSNR and EVM Correlation Study for 400G ZR Modules**
Presenter	Jeff Rahn
URL	https://www.ieee802.org/3/cw/public/21_11/fu_3cw_01_211115.pdf

The chair thanked the authors for submitting this data, which the Task Force has been seeking for a long time.

There was questions and discussion, and the Chair noted that he anticipated the EVM Ad hoc would continue discussion at their next call. Chair re-iterated the need to get EVM test data submitted.

The chair reviewed proposed liaison responses to liaisons detailed on Slide #5 of agenda deck.

Presentation #4	**Proposed Response to OIF Liaisons**
Presenter	John D'Ambrosia
URL	https://www.ieee802.org/3/cw/public/21_11/dambrosia_3cw_01a_211115_Redacted.pdf

Proposed response renamed to IEEE_802d3_to_OIF_3cw_1121_draft.pdf and updated per Task Force discussion.

Presentation #5	**Proposed Response to ITU-T Liaisons**
Presenter	John D'Ambrosia
URL	https://www.ieee802.org/3/cw/public/21_11/dambrosia_3cw_01a_211115_Redacted.pdf

Proposed response renamed to IEEE_802d3_to_ITU_3cw_1121_draft.pdf and updated per Task Force discussion.

Closing Business -

Motion	Move that the IEEE P802.3cw Task Force approve: • IEEE_802d3_to_ITU_3cw_1121_draft.pdf • IEEE_802d3_to_OIF_3cw_1121_draft.pdf with editorial license granted to the Chair (or his appointed agent) as a liaison communication from the IEEE 802.3 Working Group to ITU-T SG15 and OIF.
M:	Tom Huber
S:	Jim Weaver
Technical (>=75%)	
All (y/n/a)	Approved by unanimous consent
Results	Motion Passes

Chair reviewed future meetings. See Slide #6.
Meeting adjourned at 12:47 pm

Attendees (per IMAT)

Name	Employer	Affiliation
Abbott, John	Corning Incorporated	Corning Incorporated
Akin, Sami	Volkswagen AG	Volkswagen Ag
Anslow, Peter	INDEPENDENT	IEEE, Independent for this meeting
Beaudoin, Denis	Texas Instruments Inc.	Texas Instruments Inc.
Ben-Artsi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Bhatt, Vipul	II-VI Incorporated	II-VI Incorporated
Bois, Karl	TE Connectivity	TE Connectivity
Brandt, David	Rockwell Automation	Rockwell Automation
Brillhart, Theodore	Fluke Corporation	Fluke Corporation
Brooks, Paul	Viavi solutions GmbH	Viavi Solutions
Bruckman, Leon	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Calvin, John	Keysight Technologies	Keysight Technologies
Casher, Patrick		Foxconn Interconnect Technologies (FIT)
Chang, Jae-yong		Keysight Technologies
Chang, Yongmao	Inphi Corporation	Source Photonics
Chen, Chan	Applied Optoelectronics, Inc.	Applied Optoelectronics, Inc.
Choudhury, Golam	OFS	OFS
D'Ambrosia, John	Futurewei Technologies	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	NVIDIA	Nvidia
Deandrea, John	Finisar Corporation	Finisar Corporation
DeSanti, Claudio	Dell	Dell
Dittmann, Markus	KDPOF	KDPOF
donthu, suresh		Corning Incorporated
Dube, Kathryn	UNH-IOL	UNH-IOL
Estes, David	Spirent Communications	Spirent Communications
Feyh, German	Broadcom Corporation	Broadcom Corporation
Fritsche, Matthias	HARTING Technologie Gruppe	HARTING Electronics GmbH
Gao, Xiangrong		Huawei
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC, Marvell
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Graba, James	Broadcom Corporation	Broadcom Corporation
Hajduczenia, Marek	Charter Communications	Charter Communications
Hartmann, Stephan	Siliconally GmbH	Siliconally GmbH
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Hu, Kangmin		Innogrit
Huber, Thomas	Nokia	Nokia
Ingham, Jonathan	Huawei Technologies Co., Ltd	Huawei Technologies Canada; Huawei Technologies Co., Ltd
ISHIBE, KAZUHIKO	Anritsu Company	Anritsu Company
Isono, Hideki	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
Jackson, Kenneth	Sumitomo Electric Device Innovations, USA	Sumitomo Electric Industries, LTD
Jimenez, Andrew	Anixter Inc.	Anixter Inc.
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
Kawatsu, Yasuaki	APRESIA Systems	APRESIA Systems

Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.
Kim, Yongbum	Tenstorrent	Tenstorrent
Kimber, Eric	Semtech Ltd	Semtech Ltd
King, Roger	TRUMPF Photonic Components GmbH	TRUMPF Photonic Components GmbH
Kinningham, Alan	I-PEX CONNECTORS	I-PEX (division of Dai-Ichi Seiko)
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Koeppendoerfer, Erwin	LEONI Kabel GmbH	LEONI
Kota, Kishore	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Lackner, Hans	QoSCom GmbH	QoSCom - Quality in Communications - GmbH
Laubach, Mark	IEEE member / Self Employed	IEEE member / Self Employed
Le Cheminant, Greg	Keysight Technologies	Keysight Technologies
Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Lennartsson, Kent	Kvaser AB	Kvaser AB
Lewis, David	Lumentum Inc.	Lumentum Inc.
Lewis, Jon	Dell Technologies	Dell Technologies
Li, Pei-Rong		MediaTek Inc.
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
Lingle, Robert	OFS	OFS
Little, Terrance		Foxconn Electronics Inc.
Liu, Hai-Feng	HG Genuine	HG Genuine
Liu, Karen	Nubis Communications	Nubis Communications
Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
Maguire, Valerie	The Siemon Company	The Siemon Company
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Marques, Flavio	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
Mcclellan, Brett	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Mueller, Harald	Endress + Hauser	Endress + Hauser
Mueller, Thomas	Rosenberger	Rosenberger
Nakamoto, Edward	Spirent Communications	Spirent Communications
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Neulinger, Christian	MD Elektronik	MD Elektronik
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Xilinx	Xilinx
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.
peng, semmy		Huawei Technologies Co., Ltd
Piehler, David	Dell Technologies	Dell
Pittala, Fabio	Huawei Technologies Duesseldorf GmbH	Huawei Technologies Duesseldorf GmbH
Pitwon, Richard	Resolute Photonics	AIO Core
Potterf, Jason	Cisco Systems, Inc.	Cisco Systems, Inc.
Powell, William	INDEPENDENT	INDEPENDENT

Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Rahn, Jeffrey	Facebook	Facebook
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rettig, Thomas	Beckhoff Automation	Beckhoff Automation
Sambasivan, Sam	AT&T	AT&T
Schreiner, Stephan		Rosenberger
Sedarat, Hossein	Ethernovia	Ethernovia
Shah, Anup	Siemens Corporation	Siemens EDA
She, Qingya	Fujitsu Network Communications	Fujitsu Network Communications
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Shubochkin, Roman	OFS	OFS
Shukla, Priyank	Synopsys, Inc.	Synopsys, Inc.
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDIRES
Souvignier, Tom	Broadcom Corporation	Broadcom Corporation
Sprague, Edward	Infinera Corporation	Infinera Corporation
Stassar, Peter	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
SU, CHANGZHENG		Huawei Technologies Co., Ltd
Sun, Yi		OFS
Sydow, Carsten		Maxlinear Corp
Tan, Kan	Tektronix, Inc.	Tektronix, Inc.
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
Tracy, Nathan	TE Connectivity	TE Connectivity
Trowbridge, Stephen	Nokia	Nokia
Ulrichs, Ed	Intel Corporation	Intel Corporation
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Xinyuan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Weaver, James	Arista Networks	Arista Networks
Wey, Jun Shan	Verizon Communications	Verizon Communications
Williams, Tom	Cisco Systems, Inc.	Cisco Systems, Inc.
Withey, James	Fluke Corporation	Fluke Corporation
Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Yamada, Osamu		Yazaki Corporation
Young, James	CommScope, Inc.	CommScope
Zhang, Bo	Marvell Technology, Inc	Marvell Technology, Inc
Zhang, Tingting		Huawei Technologies Co., Ltd
Zhong, Qiwen	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zivny, Pavel	Tektronix, Inc.	Tektronix, Inc.